# ne<mark>x</mark>peria

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Should be replaced with:

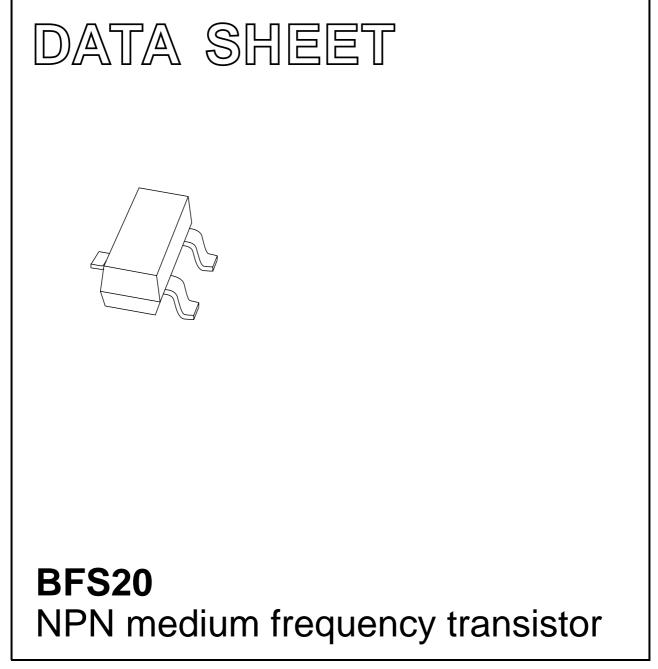
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If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

### DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 2004 Jan 5 2004 Feb 05



### FEATURES

- I<sub>C(max)</sub> = 25 mA
- V<sub>CEO(max)</sub> = 20 V
- Very low feedback capacitance (typ. 350 fF).

### APPLICATIONS

• IF and VHF thick and thin-film circuit applications.

### DESCRIPTION

NPN medium frequency transistor in a SOT23 plastic package.

### MARKING

TYPE NUMBER	MARKING CODE <sup>(1)</sup>		
BFS20	G1*		

#### Note

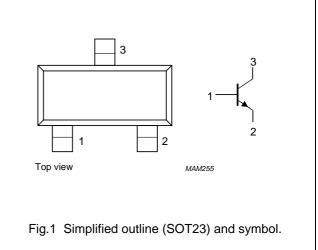
- 1. \* = p : Made in Hong Kong.
  - \* = t : Made in Malaysia.

\* = W : Made in China.

### **ORDERING INFORMATION**

PINNING

PIN	DESCRIPTION	
1	base	
2	emitter	
3	collector	



TYPE	PACKAGE				
NUMBER	NAME	DESCRIPTION VERSION			
BFS20	_	plastic surface mounted package; 3 leads	SOT23		

### LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	-	30	V
V <sub>CEO</sub>	collector-emitter voltage	open base	-	20	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	4	V
I <sub>C</sub>	collector current (DC)		-	25	mA
I <sub>CM</sub>	peak collector current		-	25	mA
P <sub>tot</sub>	total power dissipation	$T_{amb} \le 25 \ ^{\circ}C$ ; note 1	-	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

### BFS20

### BFS20

### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	500	K/W	

### Note

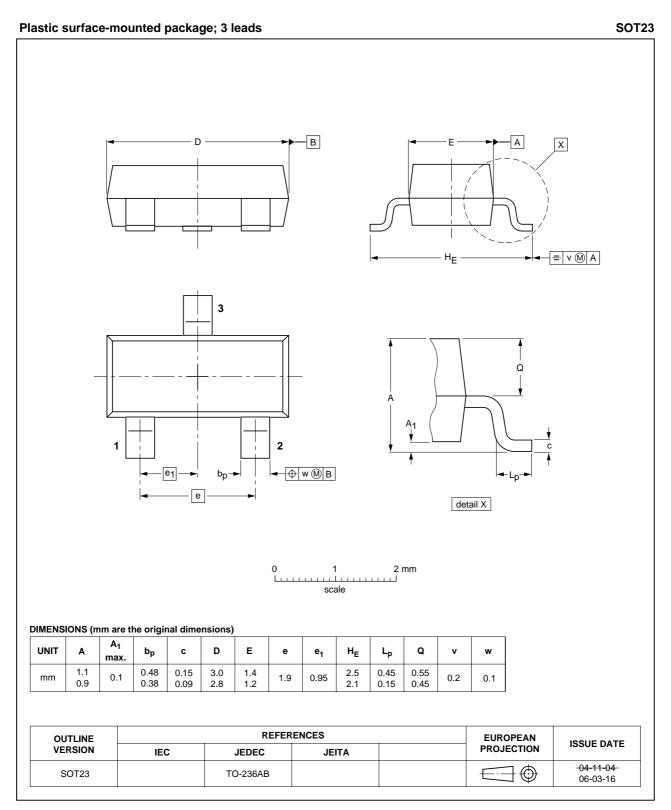
1. Transistor mounted on an FR4 printed-circuit board.

### CHARACTERISTICS

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector-base cut-off current	I <sub>E</sub> = 0; V <sub>CB</sub> = 20 V	-	-	100	nA
		I <sub>E</sub> = 0; V <sub>CB</sub> = 20 V; T <sub>j</sub> = 100 °C	-	-	10	μA
I <sub>EBO</sub>	emitter-base cut-off current	$I_{C} = 0; V_{EB} = 4 V$	-	-	100	nA
h <sub>FE</sub>	DC current gain	I <sub>C</sub> = 7 mA; V <sub>CE</sub> = 10 V	40	85	-	
V <sub>BE</sub>	base-emitter voltage	I <sub>C</sub> = 7 mA; V <sub>CE</sub> = 10 V	-	740	900	mV
Cc	collector capacitance	I <sub>E</sub> = I <sub>e</sub> = 0; V <sub>CB</sub> = 10 V; f = 1 MHz	_	1	_	pF
C <sub>re</sub>	feedback capacitance	I <sub>C</sub> = 0; V <sub>CB</sub> = 10 V; f = 1 MHz	-	350	_	fF
f <sub>T</sub>	transition frequency	I <sub>C</sub> = 5 mA; V <sub>CE</sub> = 10 V; f = 100 MHz	275	450	-	MHz

### PACKAGE OUTLINE



# BFS20

BFS20

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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